

Application Data Sheet

**Application Information**

Application Type::	Regular
Subject Matter::	Utility
Title::	Integrated Interconnect Package
Attorney Docket Number::	TI-36249 (1962-07200)
Suggested Drawing Figure::	1
Total Drawing Sheets::	8
Small Entity?::	No

**Applicant Information**

Applicant Authority type::	Inventor
Primary Citizenship Country::	US
Status::	Full Capacity
Given Name::	Navinchandra
Family Name::	KALIDAS
City of Residence::	Houston
State or Province of Residence::	TX
Country of Residence::	US
Street of mailing address::	15307 Empanada Drive
City of mailing address::	Houston
State or Province of mailing address::	TX
Country of mailing address::	US
Postal or Zip Code of mailing address::	77083

Applicant Authority type::	Inventor
Primary Citizenship Country::	US
Status::	Full Capacity
Given Name::	Jeremias
Family Name::	LIBRES

City of Residence:: Garland  
State or Province of Residence:: TX  
Country of Residence:: US  
Street of mailing address:: 2202 Meredith Lane  
City of mailing address:: Garland  
State or Province of  
mailing address:: TX  
Country of mailing address:: US  
Postal or Zip Code of  
mailing address:: 75042

**Correspondence Information**

Correspondence Customer Number:: 23494

**Representative Information**

Representative Customer Number:: 23494

**Assignee Information**

Assignee name:: Texas Instruments Incorporated  
Street of mailing address:: P.O. Box 655474, MS 3999  
City of mailing address:: Dallas  
State or Province of  
mailing address:: TX  
Country of mailing  
address:: US  
Postal or Zip Code of  
mailing address:: 75265